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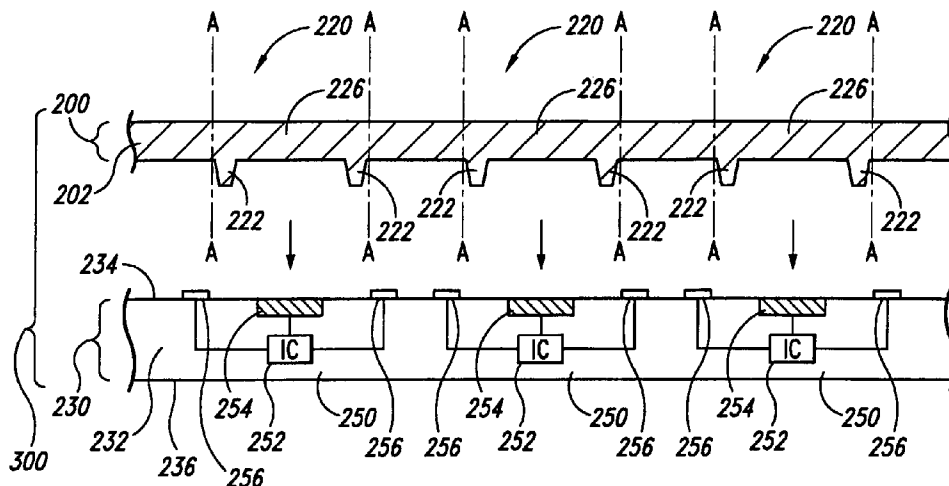
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(54) Title: COVERS FOR MICROELECTRONIC IMAGERS AND METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC IMAGERS



(57) Abstract: Methods for forming and attaching covers to microelectronic imaging units, packaging microelectronic imagers at the wafer level, and microelectronic imagers having covers that protect the image sensor are disclosed herein. In one embodiment, a method includes providing a first substrate having a plurality of covers, the covers including windows comprising regions of the first substrate and stand-offs projecting from the windows. The method continues by providing a second substrate having a plurality of microelectronic dies with image sensors, integrated circuits electrically coupled to the image sensors, and terminals electrically coupled to the integrated circuits. The method includes assembling the covers with corresponding dies so that the windows are aligned with corresponding image sensors and stand-offs contact corresponding dies inboard of the terminals and outboard of the image sensors. The first substrate is then cut to singulate the individual covers, after which the second substrate is cut to singulate individual imaging units.

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